KEVET a YAGEO company

R52 (Miniature), Class X2, 310 VAC, 110°C (Automotive Grade)

Overview

The R52 series is constructed of metallized polypropylene film encapsulated with self-extinguishing resin in a box of material that meets the requirements of UL 94 V-0. The R52 Series is ideal for harsh environmental conditions and meets the demanding Automotive Electronics Council's AEC-Q200 qualification requirements.

Applications

For worldwide use in electromagnetic interference (EMI) suppression in across-the-line applications that require X2 safety classification. Intended for use in situations in which capacitor failure would not result in exposure to electric shock. Typical applications include connection in series with the mains, capacitive power supplies and energy meters, with special emphasis in automotive applications for severe ambient conditions.

Benefits

Approvals: ENEC, UL, cUL, CQC

X2 CLASS (IEC 60384-14)

• THB Grade IIB: 85°C, 85% RH, 500 hours at

URAC acc. to IEC 60384-14
• Rated voltage: 310 VAC 50/60 Hz

Capacitance range: 0.047 – 22 μF

Lead spacing: 10.0 – 37.5 mm

• Capacitance tolerance: ±20%, ±10%

Climatic category 40/110/56, IEC 60068-1

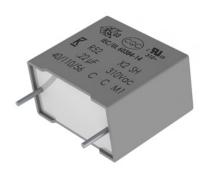
Tape & Reel in accordance with IEC 60286-2

RoHS compliant and lead-free terminations
 Operating temperature range of -40°C to +110°C

100% screening factory test at 1,900 VDC

· Self healing properties

Automotive (AEC-Q200) grade



Part Number System

R52	3	1	3470	00	P0	M
Series	Rated Voltage (VAC)	Lead Spacing (mm)	Capacitance Code (pF)	Packaging	Internal Use	Capacitance Tolerance
X2, Metallized Polypropylene	3 = 310	F = 10.0 I = 15.0 N = 22.5 R = 27.5 W = 37.5	The last three digits represent significant figures. The first digit specifies number of zeros to be added.	See Ordering Options Table	P0 P1 P2 P3	K = ±10% M = ±20%



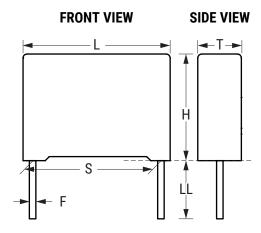
Ordering Options Table

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	Lead and Packaging Code
	Standard Lead and Packaging Options		
	Bulk (Bag) – Short Leads	4 +2/-0	00
	Pizza Pack – Short Leads	4 +2/-0	BB
	Ammo Pack	$H_0 = 18.5 \pm 0.5$	DQ
10	Other Lead and Packaging Options	11 40 5 10 5	014
	Tape & Reel (Large Reel)	$H_0 = 18.5 \pm 0.5$	CK
15	Bulk (Bag) – Short Leads	2.7 +0.5/-0	JA
	Bulk (Bag) – Short Leads	3.5 +0.5/-0	JB
22.5	Bulk (Bag) – Short Leads	4.0 +0.5/-0	JE
	Bulk (Bag) – Short Leads	3.2 +0.3/-0.2	JH
	Bulk (Bag) – Long Leads	18 ±1	JM
	Bulk (Bag) – Long Leads	30 +5/-0	40
	Bulk (Bag) – Long Leads	25 +2/-1	50
	Standard Lead and Packaging Options		
	Bulk (Tray) – Short Leads	4 +2/-0	00
	Pizza Pack - Short Leads	4 +2/-0	BB
	Tape & Reel (Large Reel)	H ₀ = 18.5 ±0.5	CK ¹
	Other Lead and Packaging Options	0	
	Bulk (Tray) – Short Leads	2.7 +0.5/-0	JA
27.5	Bulk (Tray) – Short Leads	3.5 +0.5/-0	JB
	Bulk (Tray) – Short Leads	4.0 +0.5/-0	JE
	Bulk (Tray) – Short Leads	3.2 +0.3/-0.2	JH
	Bulk (Tray) – Long Leads	18 ±1	JM
	Bulk (Tray) – Long Leads	30 +5/-0	40
	Bulk (Tray) – Long Leads	25 +2/-1	50
	, ,,	<u> </u>	
	Standard Lead and Packaging Options	4.27.0	00
	Bulk (Tray) – Short Leads Pizza Pack – Short Leads	4 +2/-0 4 +2/-0	00 BB
	Other Lead and Packaging Options	4 12/-0	00
	Bulk (Tray) – Short Leads	2.7 +0.5/-0	JA
	Bulk (Tray) – Short Leads	3.5 +0.5/-0	JB
37.5	Bulk (Tray) – Short Leads	4.0 +0.5/-0	JE
	Bulk (Tray) – Short Leads	3.2 +0.3/-0.2	JH
	Bulk (Tray) – Snort Leads	18 ±1	JM
	· ,, ·		
	Bulk (Tray) – Long Leads	30 +5/-0	40
	Bulk (Tray) – Long Leads	25 +2/-1	50

 $^{^{\}rm 1}$ Not for all sizes, see "Packaging Quantities" table.



Dimensions - Millimeters



S		Т		Н		L		F	
Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
10.0	±0.4	4.0	+0.3/-0.5	9.0	+0.3/-0.5	13.0	+0.3/-0.5	0.6	±0.05
10.0	±0.4	5.0	+0.3/-0.5	11.0	+0.3/-0.5	13.0	+0.3/-0.5	0.6	±0.05
10.0	±0.4	6.0	+0.3/-0.5	12.0	+0.3/-0.5	13.0	+0.3/-0.5	0.6	±0.05
15.0	±0.4	5.0	+0.2/-0.5	11.0	+0.1/-0.5	18.0	+0.3/-0.5	0.6	±0.05
15.0	±0.4	6.0	+0.2/-0.5	12.0	+0.1/-0.5	18.0	+0.3/-0.5	0.6	±0.05
15.0	±0.4	7.5	+0.2/-0.5	13.5	+0.1/-0.5	18.0	+0.5/-0.5	0.6	±0.05
15.0	±0.4	7.5	+0.2/-0.5	18.5	+0.1/-0.5	18.0	+0.5/-0.5	0.8	±0.05
15.0	±0.4	8.5	+0.2/-0.5	14.5	+0.1/-0.5	18.0	+0.5/-0.5	0.6	±0.05
15.0	±0.4	9.0	+0.2/-0.5	12.5	+0.1/-0.5	18.0	+0.5/-0.5	0.6	±0.05
15.0	±0.4	10.0	+0.2/-0.5	16.0	+0.1/-0.5	18.0	+0.5/-0.5	0.8	±0.05
15.0	±0.4	11.0	+0.2/-0.5	19.0	+0.1/-0.5	18.0	+0.5/-0.5	0.8	±0.05
22.5	±0.4	7.0	+0.2/-0.5	16.0	+0.1/-0.5	26.5	+0.3/-0.5	0.8	±0.05
22.5	±0.4	8.5	+0.2/-0.5	17.0	+0.1/-0.5	26.5	+0.3/-0.5	0.8	±0.05
22.5	±0.4	10.0	+0.2/-0.5	18.5	+0.1/-0.5	26.5	+0.3/-0.5	0.8	±0.05
22.5	±0.4	11.0	+0.2/-0.5	20.0	+0.1/-0.5	26.5	+0.3/-0.5	0.8	±0.05
22.5	±0.4	13.0	+0.2/-0.5	22.0	+0.1/-0.5	26.5	+0.3/-0.5	0.8	±0.05
27.5	±0.4	9.0	+0.2/-0.7	17.0	+0.1/-0.7	32.0	+0.3/-0.7	0.8	±0.05
27.5	±0.4	11.0	+0.2/-0.7	20.0	+0.1/-0.7	32.0	+0.3/-0.7	0.8	±0.05
27.5	±0.4	13.0	+0.2/-0.7	22.0	+0.1/-0.7	32.0	+0.3/-0.7	0.8	±0.05
27.5	±0.4	14.0	+0.2/-0.7	28.0	+0.1/-0.7	32.0	+0.3/-0.7	0.8	±0.05
27.5	±0.4	16.0	+0.2/-0.7	30.0	+0.1/-0.7	32.0	+0.3/-0.7	0.8	±0.05
27.5	±0.4	18.0	+0.2/-0.7	33.0	+0.1/-0.7	32.0	+0.3/-0.7	0.8	±0.05
27.5	±0.4	22.0	+0.2/-0.7	37.0	+0.1/-0.7	32.0	+0.3/-0.7	0.8	±0.05
37.5	±0.4	11.0	+0.3/-0.7	22.0	+0.1/-0.7	41.5	+0.3/-0.7	1.0	±0.05
37.5	±0.4	13.0	+0.3/-0.7	24.0	+0.1/-0.7	41.5	+0.3/-0.7	1.0	±0.05
37.5	±0.4	16.0	+0.3/-0.7	28.5	+0.1/-0.7	41.5	+0.3/-0.7	1.0	±0.05
37.5	±0.4	19.0	+0.3/-0.7	32.0	+0.1/-0.7	41.5	+0.3/-0.7	1.0	±0.05
37.5	±0.4	20.0	+0.3/-0.7	40.0	+0.1/-0.7	41.5	+0.3/-0.7	1.0	±0.05
37.5	±0.4	24.0	+0.3/-0.7	44.0	+0.1/-0.7	41.5	+0.3/-0.7	1.0	±0.05
37.5	±0.4	30.0	+0.3/-0.7	45.0	+0.1/-0.7	41.5	+0.3/-0.7	1.0	±0.05
		Note: Se	e Ordering O	ptions Tabl	e for lead ler	ngth (LL/H _o)	options.		



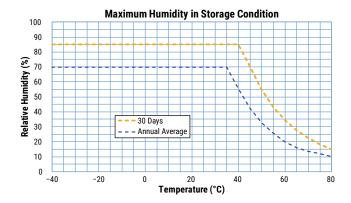
Performance Characteristics

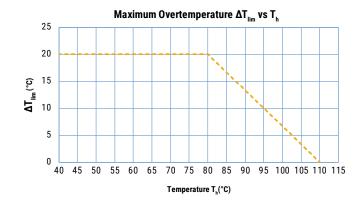
Dielectric	Polypropylene film	Polypropylene film					
Plates	Metal layer deposited by evaporation under vacuum						
Winding	Non-inductive type	Non-inductive type					
Leads	Tinned wire						
Protection	Plastic case, thermosetting	resin filled. Box material is so	olvent resistant and flame reta	ardant according to UL94.			
Related Documents	IEC 60384-14, EN 60384-	14					
Rated Voltage V _R	310 VAC (50/60 Hz)						
Recommended DC Voltage	≤ 630 VDC						
Capacitance Range	0.047 - 22 μF						
Capacitance Values	E6 series (IEC 60063) me	asured at 1 kHz and +20 ±1°	°C				
Capacitance Tolerance	±10%, ±20%						
Temperature Range	-40°C to +110°C						
Climatic Category	40/110/56 IEC 60068-1						
	Storage time: ≤ 24 months from the date marked on the label package						
	Average relative humidity per year ≤ 70%						
Storage Conditions	RH ≤ 85% for 30 days randomly distributed throughout the year						
	Dew is absent						
	Temperature: -40 to 80°C (see "Maximum Humidity in Storage Conditions" graph below)						
Approvals	ENEC, UL, cUL, CQC						
Dissipation Factor (tanδ)	C ≤ 0	.1 μF	C > 0).1 μF			
at 1 kHz at 25 °C ±5°C	0.3	3%	0.:	2%			
Test Voltage Between Terminals	The 100% screening factory test is carried out at 1,900 VDC. The voltage level is selected to meet the requirements in applicable equipment standards. All electrical characteristics are checked after the test. This test cannot be repeated, as there is a risk of damaging the capacitor. KEMET is not liable in such cases for any failures.						
	Measured at +25°C ±5°C, according to IEC 60384-2						
		Minimum Values B	etween Terminals				
Insulation Resistance	Voltage Charge	Voltage Charge Time	C ≤ 0.33 µF	C > 0.33 µF			
* Timinal value	100 VDC	1 minute	$\geq 1 \cdot 10^{5} \mathrm{M}\Omega$ ($\geq 5 \cdot 10^{5} \mathrm{M}\Omega$)*	≥ 30,000 MΩ • μF (≥ 150,000 MΩ • μF)*			

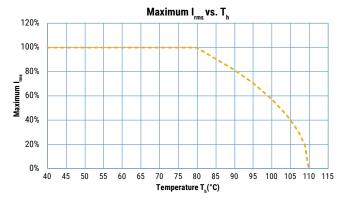
^{*} Typical value



Performance Characteristics cont.







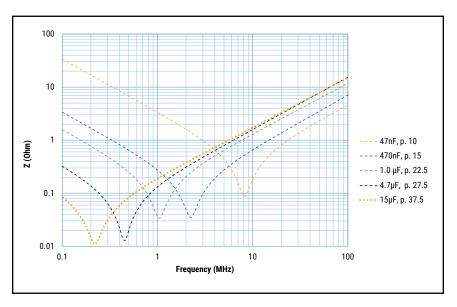
 T_h is the maximum ambient temperature surrounding the capacitor or hottest contact point (e.g. tracks), whichever is higher, in the worst operation conditions in $^{\circ}$ C.



Qualification

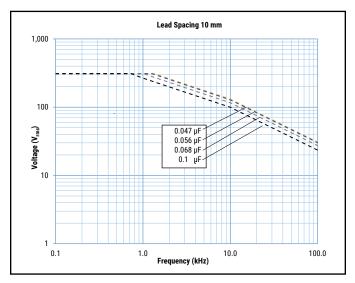
Automotive Grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. For additional information regarding the Automotive Electronics Council and AEC-Q200, please visit the website at www.aecouncil.com.

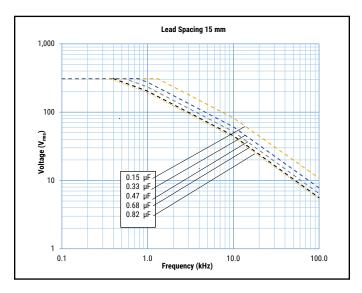
Impedance Graph

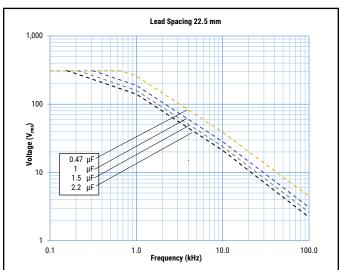


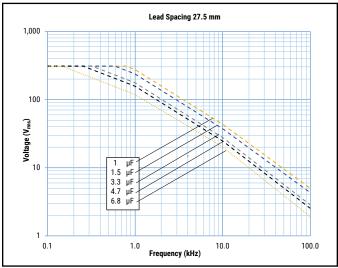


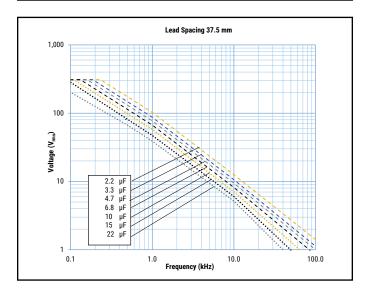
Maximum Voltage (V_{rms}) Versus Frequency (Sinusoidal Waveform/Th ≤ 80 °C)





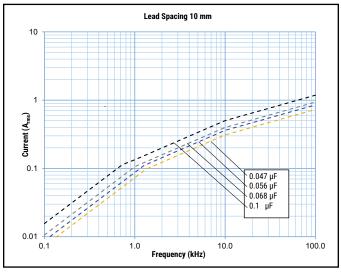


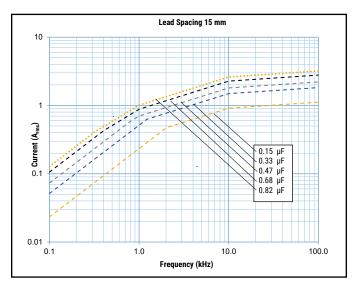


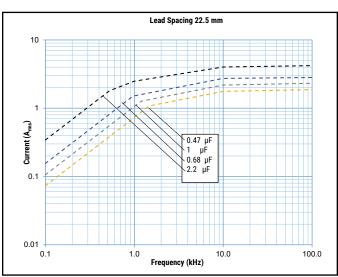


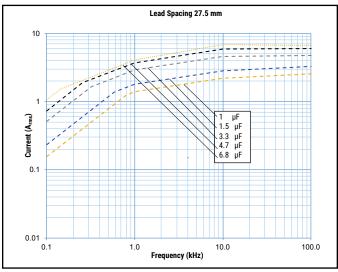


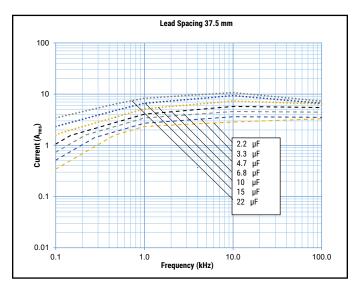
Maximum Current (I_{rms}) Versus Frequency (Sinusoidal Waveform/Th ≤ 80°C)













Environmental Test Data

Test	IEC Publication	Procedure			
Endurance	IEC 60384-14	1.25 x V _R VAC 50 Hz, once every hour increase to 1,000 VAC for 0.1 second, 1,000 hours at upper rated temperature			
Vibration	MIL-STD-202 Method 204	5 G for 20 minutes, 12 cycles each of 3 orientations. Use 8" X 5" PCB, 0.031" thick. 7 secure points on one 8" side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from $10-2,000$ Hz.			
Mechanical Shock	MIL-STD-202 Method 213	Figure 1 of Method 213. Condition C			
Temperature Cycling	JESD22-Method JA-104	1,000 cycles (-40°C to 110°C) Note: Measurement at 24 ±4 hours after test conclusion. 30 minute maximum dwell time at each temperature extreme. 1 minute maximum transition time.			
Active Flammability	IEC 60384-14	V_R + 20 surge pulses at 2.5 kV (pulse every 5 seconds)			
Passive Flammability	IEC 60384-14	IEC 60384-1, IEC 60695-11-5 Needle flame test			
Diagod Uyunidiku		85°C/85% RH and 240 VAC, 1,000 hours Capacitance change (ΔC/C): ≤ 10% Dissipation factor change (Δtan δ): ≤ 15 * 10^{-3} (at 1 kHz) Insulation resistance Rins or time constant τ = CR Rins: ≥ 50% of initial limit			
Biased Humidity	According to Grade IIB	85°C/85% RH and 310 VAC, 500 hours Capacitance change (Δ C/C): \leq 10% Dissipation factor change (Δ tan δ): \leq 24 * 10 ⁻³ (at 10 kHz) for C \leq 1 μ F Dissipation factor change (Δ tan δ): \leq 15 * 10 ⁻³ (at 1 kHz) for C > 1 μ F Insulation resistance Rins or time constant τ = CR Rins: \geq 50% of initial limit			

Approvals

Certification Body	Mark	Specification	File Number
IMQ S-p.A.		EN/IEC 60384-14	CA08.00231
UL	c SU ®us	UL 60384-14 and CAN/CSA E60384-14 (310 VAC)	E97797
cqc	Cec	IEC 60384-14	CQC20001263098 CQC20001263099 CQC20001263100 CQC20001263101 CQC20001263102 CQC20001263103



Environmental Compliance

All KEMET EMI capacitors are RoHS Compliant.



Table 1 – Ratings & Part Number Reference

Capacitance	Dime	ensions ir	n mm	Lead Spacing	dV/dt	KEMET	Legacy
Value (µF)	Т	Н	L	(S)	(V/µs)	Part Number	Part Number
0.047	4.0	9.0	13.0	10.0	500	523F2470(1)P0(2)	R523F2470(1)P0(2)
0.056	5.0	11.0	13.0	10.0	500	523F2560(1)P0(2)	R523F2560(1)P0(2)
0.068	5.0	11.0	13.0	10.0	500	523F2680(1)P0(2)	R523F2680(1)P0(2)
0.10	6.0	12.0	13.0	10.0	500	523F3100(1)P0(2)	R523F3100(1)P0(2)
0.10	5.0	11.0	18.0	15.0	400	523I3100(1)P0(2)	R523I3100(1)P0(2)
0.15	5.0	11.0	18.0	15.0	400	523I3150(1)P0(2)	R523I3150(1)P0(2)
0.22	6.0	12.0	18.0	15.0	400	523I3220(1)P0(2)	R523I3220(1)P0(2)
0.33	7.5	13.5	18.0	15.0	400	523I3330(1)P0(2)	R523I3330(1)P0(2)
0.33	9.0	12.5	18.0	15.0	400	523I3330(1)P1(2)	R523I3330(1)P1(2)
0.47	8.5	14.5	18.0	15.0	400	523I3470(1)P0(2)	R523I3470(1)P0(2)
0.47	9.0	12.5	18.0	15.0	400	523I3470(1)P1(3)	R523I3470(1)P1(3)
0.47	7.5	18.5	18.0	15.0	400	523I3470(1)P3(2)	R523I3470(1)P3(2)
0.56	10.0	16.0	18.0	15.0	400	523I3560(1)P0(2)	R523I3560(1)P0(2)
0.68	10.0	16.0	18.0	15.0	400	523I3680(1)P1(3)	R523l3680(1)P1(3)
0.68	11.0	19.0	18.0	15.0	400	523I3680(1)P0(2)	R523I3680(1)P0(2)
0.82	11.0	19.0	18.0	15.0	400	523I3820(1)P0(3)	R523I3820(1)P0(3)
1.0	12.0	20.0	18.0	15.0	400	523I4100(1)P0(3)	R523I4100(1)P0(3)
0.47	7.0	16.0	26.5	22.5	200	523N3470(1)P0(2)	R523N3470(1)P0(2)
0.56	7.0	16.0	26.5	22.5	200	523N3560(1)P0(2)	R523N3560(1)P0(2)
0.68	7.0	16.0	26.5	22.5	200	523N3680(1)P0(2)	R523N3680(1)P0(2)
0.82	8.5	17.0	26.5	22.5	200	523N3820(1)P0(2)	R523N3820(1)P0(2)
1.0	8.5	17.0	26.5	22.5	200	523N4100(1)P1(3)	R523N4100(1)P1(3)
1.0	10.0	18.5	26.5	22.5	200	523N4100(1)P0(2)	R523N4100(1)P0(2)
1.5	10.0	18.5	26.5	22.5	200	523N4150(1)P1(3)	R523N4150(1)P1(3)
1.5	11.0	20.0	26.5	22.5	200	523N4150(1)P0(2)	R523N4150(1)P0(2)
2.2	13.0	22.0	26.5	22.5	200	523N4220(1)P0(3)	R523N4220(1)P0(3)
1.0	9.0	17.0	32.0	27.5	150	523R4100(1)P0(2)	R523R4100(1)P0(2)
1.5	11.0	20.0	32.0	27.5	150	523R4150(1)P0(2)	R523R4150(1)P0(2)
2.2	13.0	22.0	32.0	27.5	150	523R4220(1)P0(2)	R523R4220(1)P0(2)
3.3	14.0	28.0	32.0	27.5	150	523R4330(1)P0(2)	R523R4330(1)P0(2)
4.7	14.0	28.0	32.0	27.5	150	523R4470(1)P1(3)	R523R4470(1)P1(3)
4.7	16.0	30.0	32.0	27.5	150	523R4470(1)P2(2)	R523R4470(1)P2(2)
4.7	18.0	33.0	32.0	27.5	150	523R4470(1)P0(2)	R523R4470(1)P0(2)
6.8	22.0	37.0	32.0	27.5	150	523R4680(1)P0(2)	R523R4680(1)P0(2)
2.2	11.0	22.0	41.5	37.5	100	523W4220(1)P0(2)	R523W4220(1)P0(2)
3.3	13.0	24.0	41.5	37.5	100	523W4330(1)P0(2)	R523W4330(1)P0(2)
4.7	16.0	28.5	41.5	37.5	100	523W4470(1)P0(2)	R523W4470(1)P0(2)
6.8	19.0	32.0	41.5	37.5	100	523W4680(1)P0(2)	R523W4680(1)P0(2)
10.0	20.0	40.0	41.5	37.5	100	523W5100(1)P0(2)	R523W5100(1)P0(2)
15.0	24.0	44.0	41.5	37.5	100	523W5150(1)P0(2)	R523W5150(1)P0(2)
22.0	30.0	45.0	41.5	37.5	100	523W5220(1)P0(2)	R523W5220(1)P0(2)
Capacitance Value (µF)	B (mm)	H (mm)	L (mm)	Lead Spacing (p)	dV/dt (V/μs)	KEMET Part Number	Legacy Part Number

⁽¹⁾ Insert lead and packaging code. See Ordering Options Table for available options.

⁽²⁾ $M = \pm 20\%$, $K = \pm 10\%$

⁽³⁾ $M = \pm 20\%$ (only available tolerance).



Soldering Process

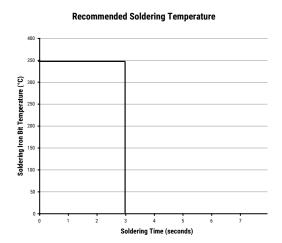
The implementation of the RoHS directive has resulted in the selection of SnAuCu (SAC) alloys or SnCu alloys as primary solder material. This has increased the liquidus temperature from 183° C for SnPb eutectic alloys to $217 - 221^{\circ}$ C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher preheat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is $160 - 170^{\circ}$ C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 - 15 mm). Great care must be taken during soldering. The recommended solder profiles from KEMET should be used. Consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid quideline for successful soldering. See Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the above-recommended limits may result to degradation of or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface mount components. Insert through-hole parts after curing surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum two soldering cycles is recommended. Allow time for the capacitor surface temperature to return to normal temperature before performing the second soldering cycle.

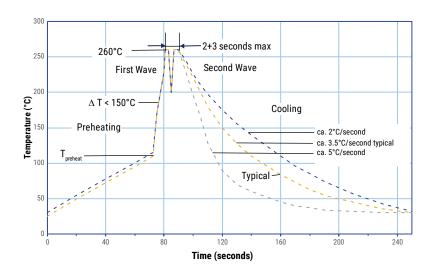
Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



The soldering iron tip temperature should be set at 350°C (+10°C maximum), with the soldering duration not to exceed more than 3 seconds.

Wave Soldering Recommendations





Soldering Process cont.

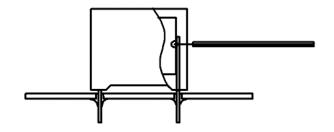
Wave Soldering Recommendations cont.

1. The table indicates the maximum set-up temperature of the soldering process.

Dielectric	Maxi Prel Tempe	heat	Maximum Peak Soldering Temperature		
Film Material	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	270°C	270°C	
Polypropylene	110°C	130°C	260°C	270°C	
Paper	130°C	140°C	270°C	270°C	
Polyphenylene Sulphide	150°C	160°C	270°C	270°C	

2. The maximum temperature measured inside the capacitor: set the temperature so that the maximum temperature inside the element is below the limit.

Dielectric Film Material	Maximum Temperature Measured Inside the Element		
Polyester	160°C		
Polypropylene	110°C		
Paper	160°C		
Polyphenylene Sulphide	160°C		



Temperature monitored inside the capacitor.

Selective Soldering Recommendations

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath as it is in normal flow soldering, without touching the solder. When the board is over the bath, it is stopped. Pre-designed solder pots are lifted from the bath with molten solder, only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document. **However, instead of two baths, there is only one with a time from 3 – 10 seconds.** In selective soldering, the risk of overheating is greater than in double wave flow soldering, and great care must be taken so that the parts do not overheat.



Mounting

Resistance to Vibration and Mechanical Shock

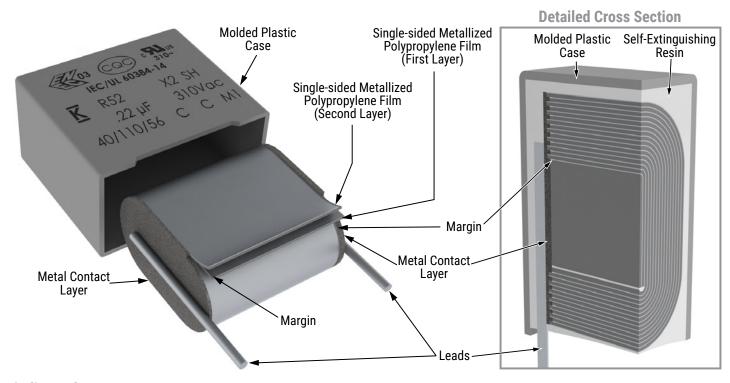
AEC-Q200 Mechanical Stress Tests:					
Mechanical Shock	MIL-SDT-202 Method 213	Test condition C Peak value 100 g, duration 6 ms, half-sine-wave (see MIL-HDBK for details)			
Vibration	MIL-SDT-202 Method 204	5 G for 20 minutes, 12 cycles each of 3 orientations Use 8"X5" PCB, 0.031" thick. 7 secure points on one 8" side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz.			

The capacitors are designed for PCB mounting.

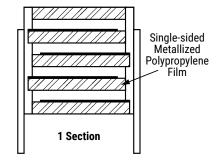
The stand-off pipes must be in good contact with the printed circuit board.

The capacitor body has to be properly fixed (e.g. clamped or glued).

Construction



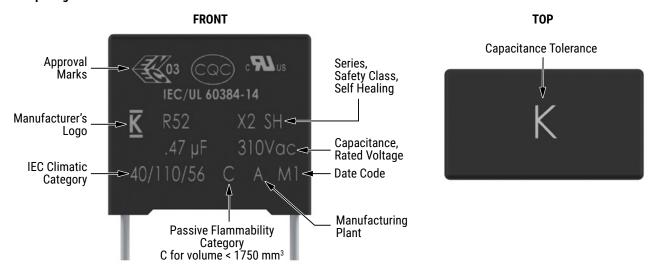
Winding Scheme





Marking

Lead Spacing 10 mm

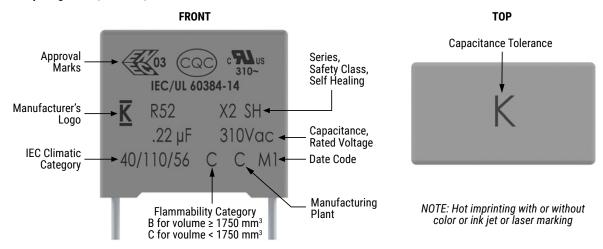


Manufacturing Date Code (IEC-60062)							
Year	Code	Year	Code	Month	Code	Month	Code
2010	Α	2020	М	January	1	July	7
2011	В	2021	N	February	2	August	8
2012	С	2022	Р	March	3	September	9
2013	D	2023	R	April	4	October	0
2014	Е	2024	S	May	5	November	N
2015	F	2025	T	June	6	December	D
2016	Н	2026	U				
2017	J	2027	V				
2018	K	2028	W				
2019	L	2029	Х				

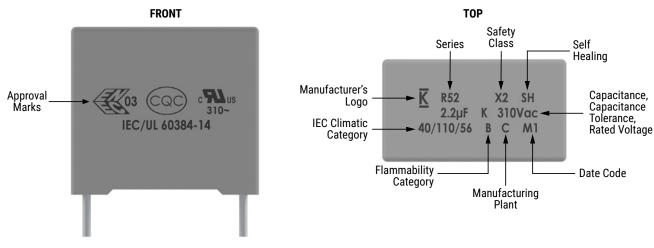


Marking cont.

Lead Spacing 15 mm, 22.5 mm, and 27.5 mm



Lead Spacing 22.5, 27.5 mm (alternatives*) and 37.5 mm



	*Differences	are caus	sed by te	chnology
1	(clichee, laser,			

Manufacturing Date Code (IEC-60062)							
Year	Code	Year	Code	Month	Code	Month	Code
2010	Α	2020	М	January	1	July	7
2011	В	2021	N	February	2	August	8
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2013	D	2023	R	April	4	October	0
2014	E	2024	S	May	5	November	N
2015	F	2025	Т	June	6	December	D
2016	Н	2026	U				
2017	J	2027	V				
2018	K	2028	W	1			
2019	L	2029	Х				



Packaging Quantities

Lead Spacing (mm)	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Bulk Long Leads	Standard Reel ø 355 mm	Large Reel ø 500 mm	Ammo Taped	Pizza
Lead and Packaging Code:			00 - JA - JB - JE - JH	JM - 40 - 50	GY	СК	DQ	ВВ	
	4	9	13	2,000	1,800	750	1,500	1,000	
10	5	11	13	1,300	1500	600	1,250	800	
	6	12	13	1,000	1200	500	1000	680	
F 44 40 0000 4000 4000 4000 4000									
	5	11	18	2,000	1,000	600	1,250	800	1,122
	6	12	18	1,750	900	500	1,000	680	935
	7.5	13.5	18	1,000	700	350	800	500	748
4=	7.5	18.5	18	900	500	-	800	500	748
15	8.5	14.5	18	1,000	500	300	700	440	663
	9	12.5	18	1,000	520	270	650	410	612
	10	16	18	750	500	270	600	380	561
	11	19	18	450	350	-	500	340	510
	12	20	18	400	350	220	450	300	459
	7	16	26.5	700	500	-	550	380	564
	8.5	17	26.5	468	300	-	450	280	468
22.5	10	18.5	26.5	396	300	_	350	235	396
22.0	11	20	26.5	360	250	_	350	217	360
	13	22	26.5	300	200	_	300	-	300
	.0		20.0		200		300		000
	9	17	32	816	408	-	450	-	370
27.5	11	20	32	560	336	-	350	-	300
	13	22	32	480	288	-	300	-	250
	14	28	32	352	176	-	-	-	230
	16	30	32	288	144	-	-	-	200
	18	33	32	256	128	-	-	-	170
	22	37	32	168	112	-	-	-	150
37.5	11	22	41.5	420	252	-	-	-	210
	13	24	41.5	360	216	-	-	-	175
	16	28.5	41.5	216	108	-	-	-	140
	19	32	41.5	192	96	-	-	-	119
	20	40	41.5	126	84	-	-	-	112
	24	44	41.5	108	72	-	-	-	91
	30	45	41.5	90	60	-	-	-	77



Lead Taping & Packaging (IEC 60286-2)

Figure 1 Lead Spacing 10 mm

Figure 2 Lead Spacing 15 mm

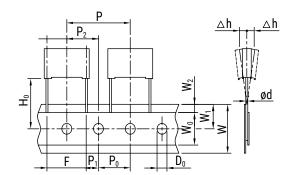
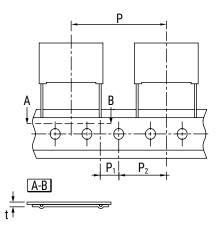


Figure 3 Lead Spacing 22.5 – 27.5 mm



Taping Specification

		Dimensions (mm)					
Description	Symbol						
Description	Cymbol	10	15	22.5	27.5	Tol.	
		Fig. 1	Fig. 2	Fig. 3	Fig. 3		
Lead wire diameter	d	0.6	0.6-0.8	0.8	0.8	±0.05	
Taping lead space	Р	25.4	25.4	38.1	38.1	±1	
Feed hole lead space *	P_0	12.7	12.7	12.7	12.7	±0.2 **	
Centering of the lead wire	P ₁	7.7	5.2	7.8	5.3	±0.7	
Centering of the body	P ₂	12.7	12.7	19.05	19.05	±1.3	
Lead spacing (pitch) ***	F	10	15	22.5	27.5	+0.6/-0.1	
Component alignment	Δh	0	0	0	0	±2	
Height of component from tape center	H ₀ ****	18.5	18.5	18.5	18.5	±0.5	
Carrier tape width	W	18	18	18	18	+1/-0.5	
Hold down tape width	W_{0}	9	10	10	10	Minimum	
Hole position	W ₁	9	9	9	9	±0.5	
Hold down tape position	W ₂	3	3	3	3	Maximum	
Feed hole diameter	D ₀	4	4	4	4	±0.2	
Total tape thickness	t	0.7	0.7	0.7	0.7	±0.2	

^{* 15} mm also available

^{**} Maximum of 1 mm on 20 lead spaces

^{***} Pitches 15 mm and 10 mm taped to 7.5 mm (crimped leads) available upon request

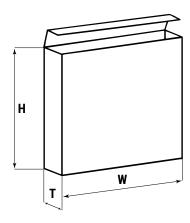
^{****} H_0 = 16.5 mm is available upon request



Lead Taping & Packaging (IEC 60286-2) cont.

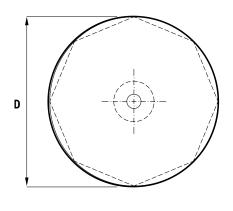
Ammo Specifications

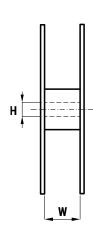
Dimensions (mm)						
Н	W	Т				
360	340	59				



Reel Specifications

Reel Size	Dimensions (mm)				
Reel Size	D	Н	W		
Standard	355	30	EE Mavimum		
Large	500	25	55 Maximum		







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